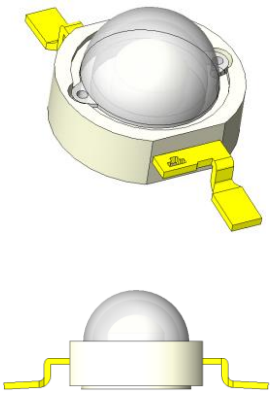
ProLight Opto
Technology Corporation



ProLight PM2B-1LWE
PM2B-1LxE-Rx
1W High CRI Power LED
Technical Datasheet
Version: 1.2

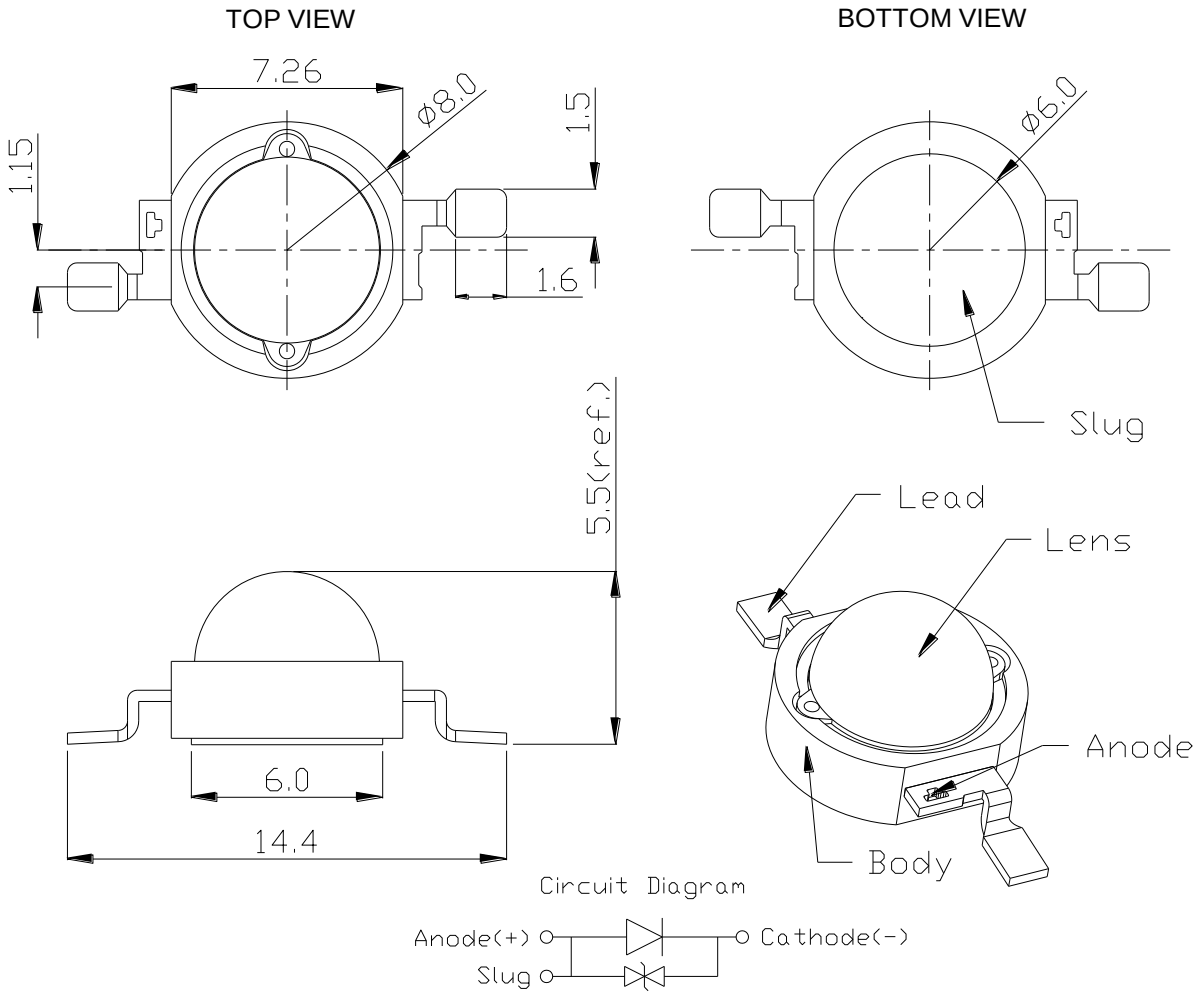
Features

- High Color rendering index (CRI>70 and CRI Typ.80)
- Low-temp. & lead free reflow soldering
- Good color uniformity
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV
- Superior ESD protection

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

Emitter Mechanical Dimensions



Notes:
1. The Anode side of the device is denoted by a hole in the lead frame.
2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. All dimendions without tolerances are for reference only.
6. Please do not bend the leads of the LED, otherwise it will damage the LED.
7. **Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 350mA, T_J = 25°C

Radiation Pattern	Color	Part Number Emitter	Lumious Flux Φ_V (lm) Minimum	Typical	CRI Typical
Lambertian	White	PM2B-1LWE	87.4	105	75
	Warm White	PM2B-1LVE-R7	67.2	80	75
	White	PM2B-1LWE-R8	67.2	86	80
	Warm White	PM2B-1LVE-R8	58.9	75	80

- ProLight maintains a tolerance of ± 10% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 350mA, T_J = 25°C

Color	Forward Voltage V_F (V) Min.	Typ.	Max.	Thermal Resistance Junction to Slug (°C/ W)
White	2.85	3.5	4.1	10
Warm White	2.85	3.5	4.1	10

Optical Characteristics at 350mA, T_J = 25°C

Color	Color Temperature CCT Min.	Typ.	Max.	Total included Angle (degrees) $\theta_{0.90V}$	Viewing Angle (degrees) $2\,\theta_{1/2}$
White	4100 K	5500 K	10000 K	180	130
Warm White	2700 K	2875 K	3050 K	180	130

- ProLight maintains a tolerance of ± 5% for CCT measurements.

Absolute Maximum Ratings

Parameter	White/Warm White
DC Forward Current (mA)	350
Peak Pulsed Forward Current (mA)	500
Average Forward Current (mA)	350
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)
LED Junction Temperature (˚C)	120
Aluminum-core PCB Temperature (˚C)	105
Storage & Operating Temperature (˚C)	-40 to +105
Soldering Temperature(˚C)	235°C

Forward Voltage Bin Structure

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
White	A	2.85	3.10
	B	3.10	3.35
	D	3.35	3.60
	E	3.60	3.85
	F	3.85	4.10
Warm White	A	2.85	3.10
	B	3.10	3.35
	D	3.35	3.60
	E	3.60	3.85
	F	3.85	4.10

- ProLight maintains a tolerance of ± 0.1 for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

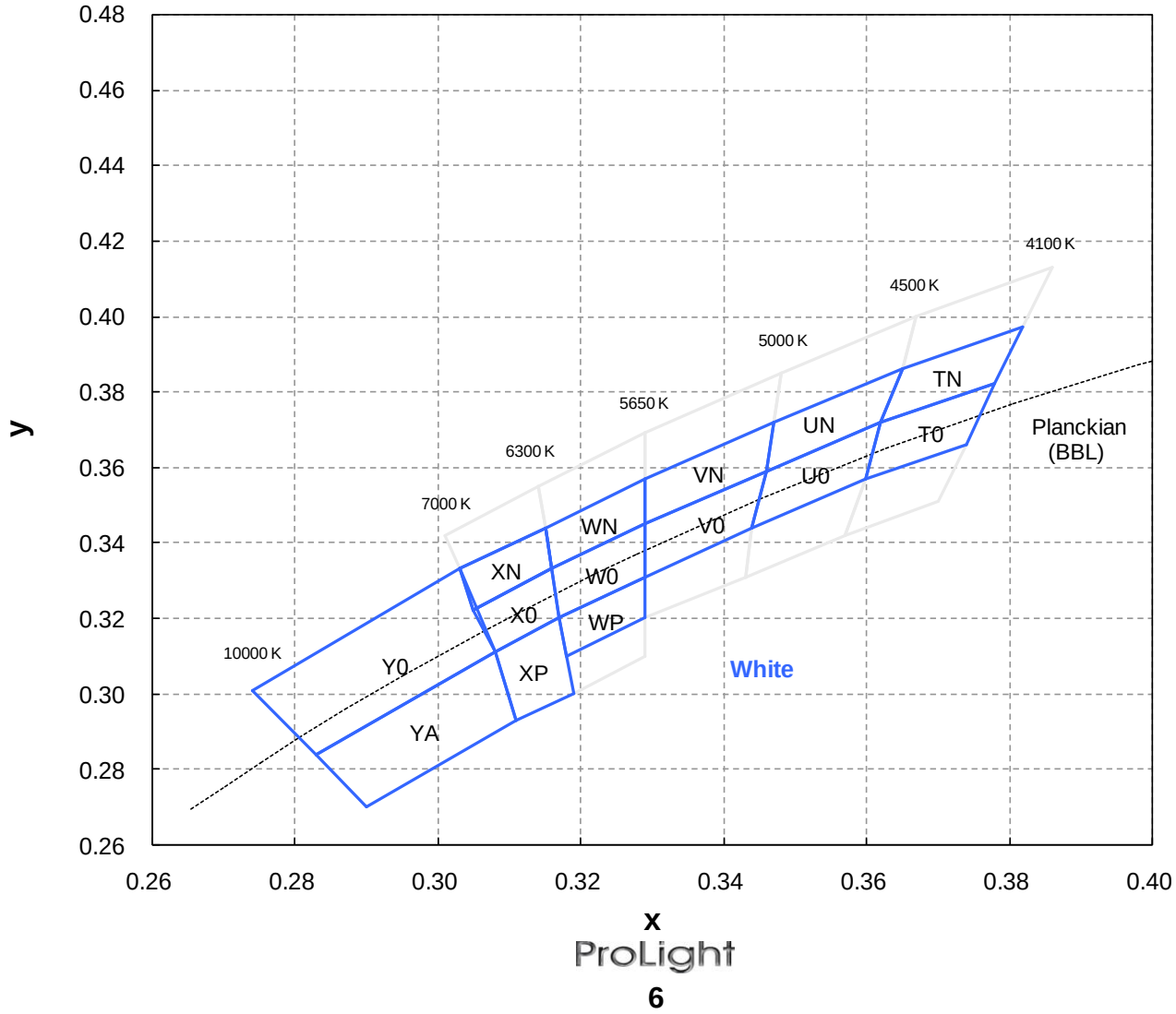
Photometric Luminous Flux Bin Structure

Part Number	Bin Code	Minimum Photometric Flux (lm)	Maximum Photometric Flux (lm)	Available Color Bins
PM2B-1LWE	U1	87.4	99.6	All
	U2	99.6	113.6	All
PM2B-1LVE-R7	T1	67.2	76.6	All
	T2	76.6	87.4	N0【1】
PM2B-1LWE-R8	T1	67.2	76.6	All
	T2	76.6	87.4	All
	U1	87.4	99.6	【1】
PM2B-1LVE-R8	S2	58.9	67.2	All
	T1	67.2	76.6	All
	T2	76.6	87.4	【1】

- ProLight maintains a tolerance of ± 10% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- 【1】The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Color Bin

White Binning Structure Graphical Representation



Color Bins

White Bin Structure

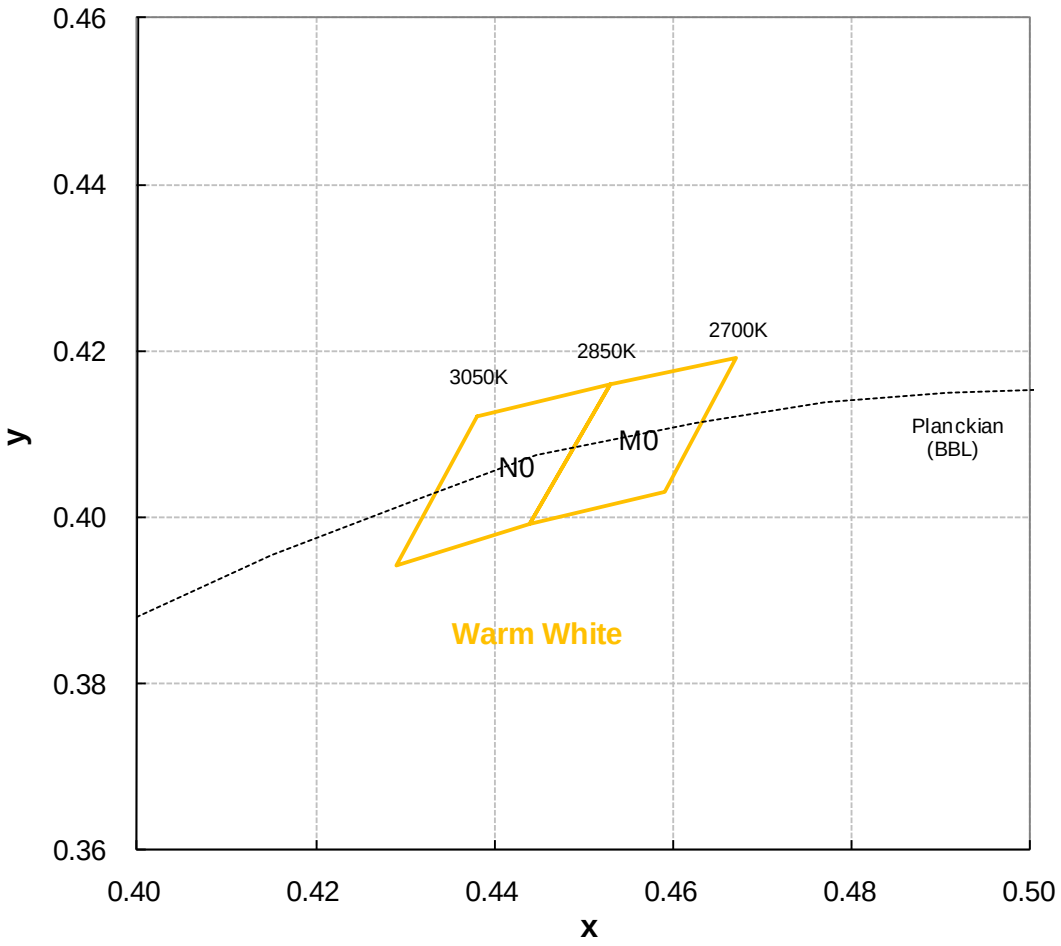
Bin Code	x	y	Typ. CCT (K)	Bin Code	x	y	Typ. CCT (K)
T0	0.378	0.382	4300	WN	0.329	0.345	5970
	0.374	0.366			0.316	0.333	
	0.360	0.357			0.315	0.344	
	0.362	0.372			0.329	0.357	
TN	0.382	0.397	4300	WP	0.329	0.331	5970
	0.378	0.382			0.329	0.320	
	0.362	0.372			0.318	0.310	
	0.365	0.386			0.317	0.320	
U0	0.362	0.372	4750	X0	0.308	0.311	6650
	0.360	0.357			0.305	0.322	
	0.344	0.344			0.316	0.333	
	0.346	0.359			0.317	0.320	
UN	0.365	0.386	4750	XN	0.305	0.322	6650
	0.362	0.372			0.303	0.333	
	0.346	0.359			0.315	0.344	
	0.347	0.372			0.316	0.333	
V0	0.329	0.331	5320	XP	0.308	0.311	6650
	0.329	0.345			0.317	0.320	
	0.346	0.359			0.319	0.300	
	0.344	0.344			0.311	0.293	
VN	0.329	0.345	5320	Y0	0.308	0.311	8000
	0.329	0.357			0.283	0.284	
	0.347	0.372			0.274	0.301	
	0.346	0.359			0.303	0.333	
W0	0.329	0.345	5970	YA	0.308	0.311	8000
	0.329	0.331			0.311	0.293	
	0.317	0.320			0.290	0.270	
	0.316	0.333			0.283	0.284	

- Tolerance on each color bin (x , y) is ± 0.01

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Bins

Warm White Binning Structure Graphical Representation



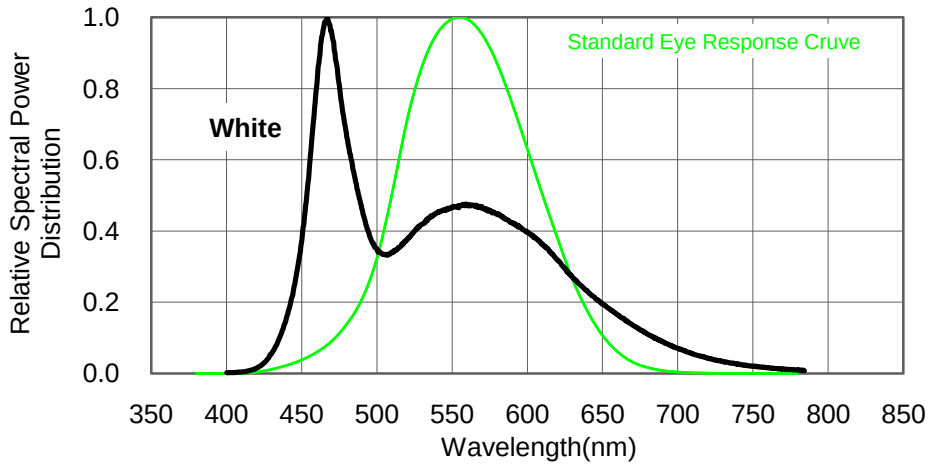
Warm White Bin Structure

Bin Code	x	y	Typ. CCT (K)	Bin Code	x	y	Typ. CCT (K)
M0	0.453 0.444 0.459 0.467	0.416 0.399 0.403 0.419	2770	N0	0.438 0.429 0.444 0.453	0.412 0.394 0.399 0.416	2950

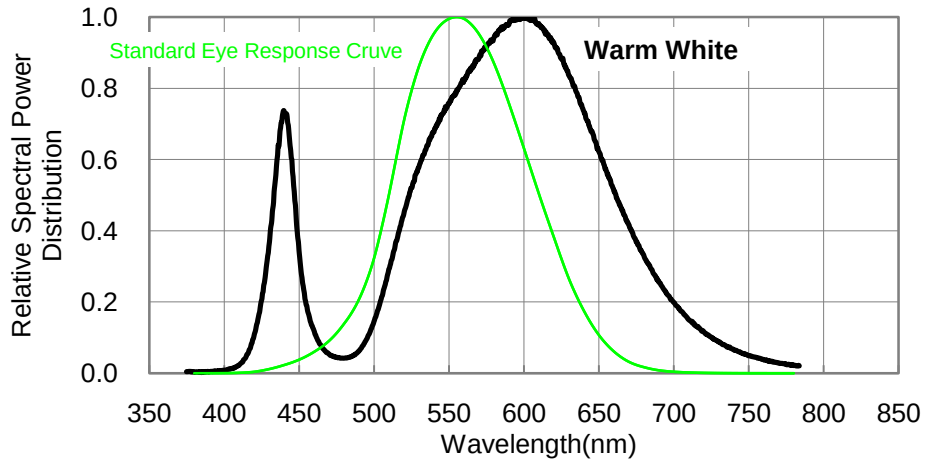
● Tolerance on each color bin (x , y) is ± 0.01

Color Spectrum, T_J = 25°C

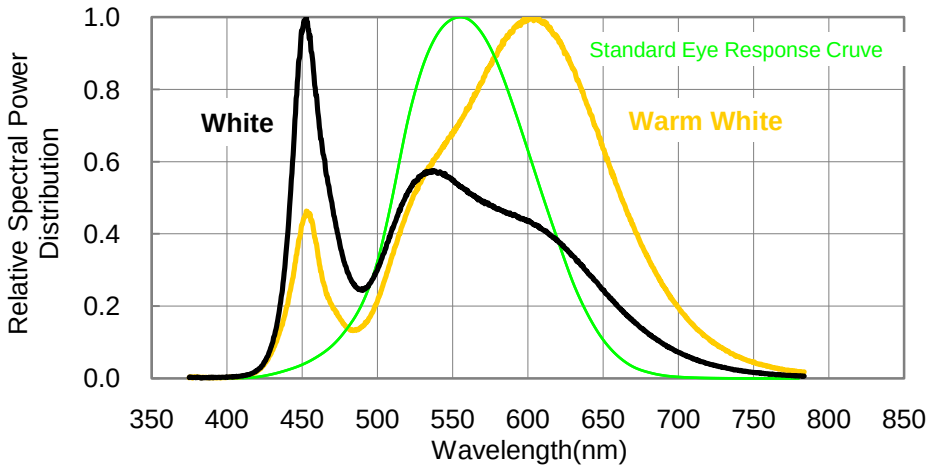
1. White



2. Warm White For R7

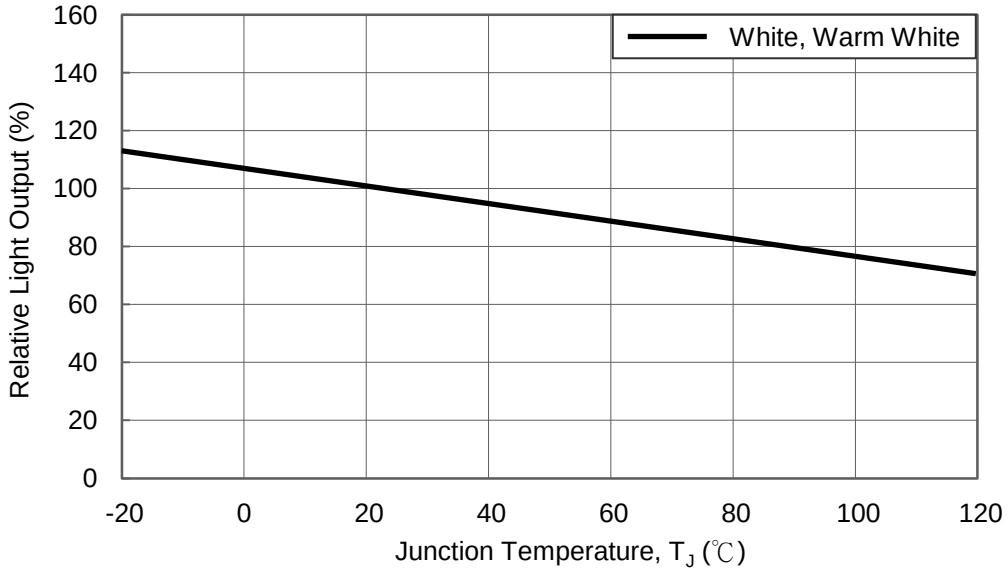


3. White、Warm White For R8



Light Output Characteristics

Relative Light Output vs. Junction Temperature at 350mA



Forward Current Characteristics, T_J = 25°C

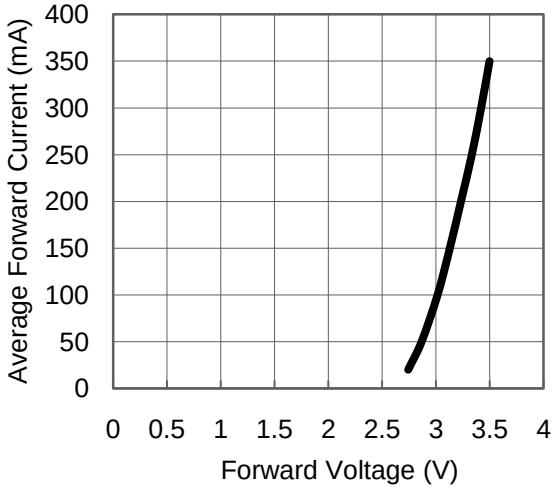


Fig 1. Forward Current vs. Forward Voltage for White, Warm White.

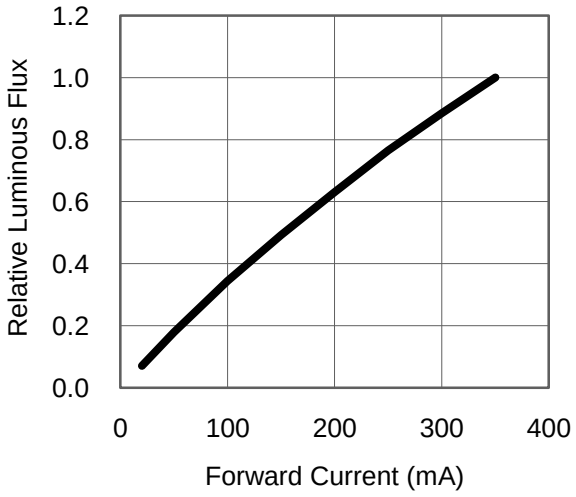
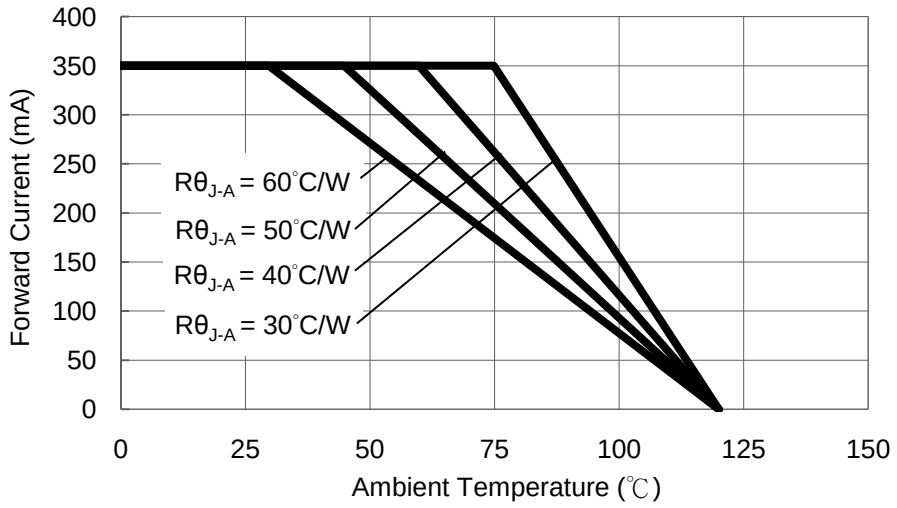


Fig 2. Relative Luminous Flux vs. Forward Current for White, Warm White at Tj=25℃ maintained.

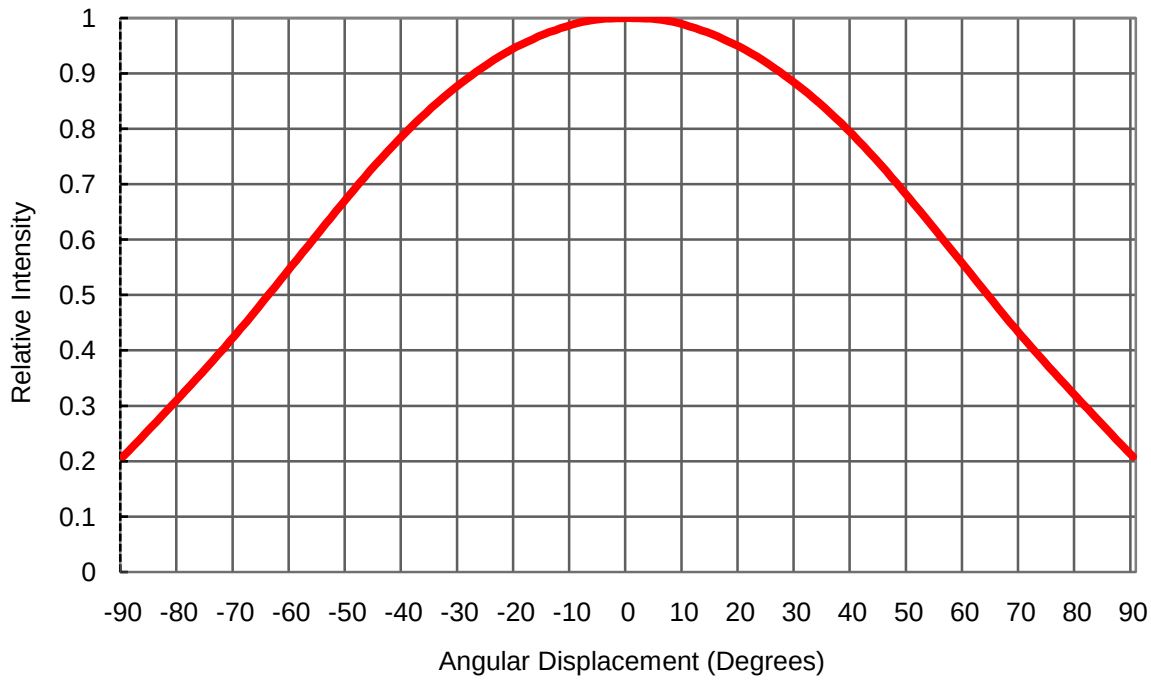
Ambient Temperature vs. Maximum Forward Current

1. White, Warm White (T_{JMAX} = 120°C)



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I_F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Non-operating Thermal Shock (TMSK)	-40°C to 120°C, 20 min. dwell, <20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.

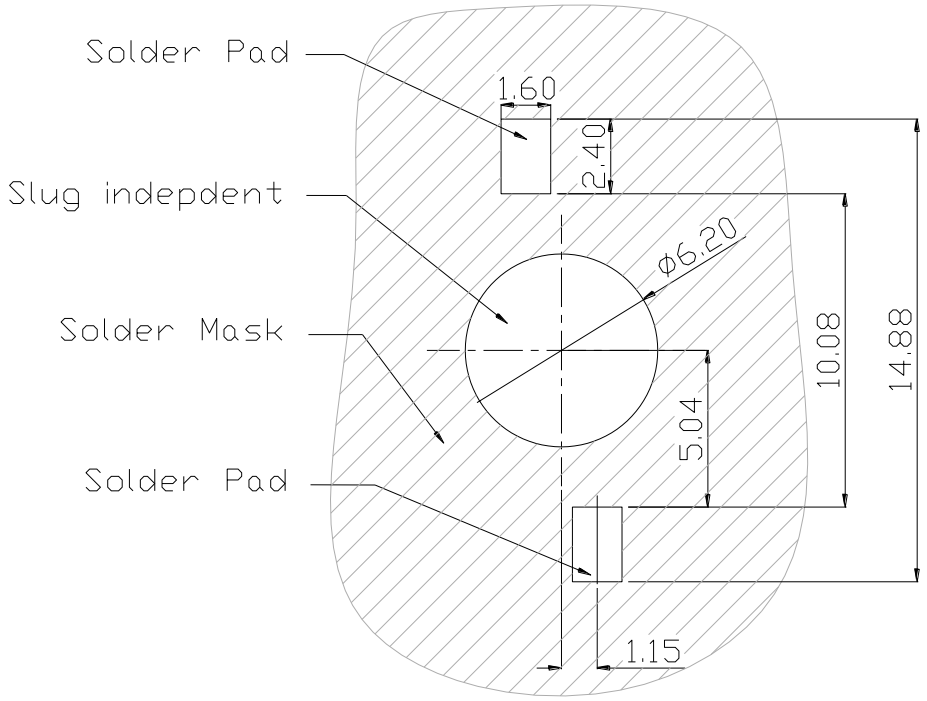
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V_F)	I_F = max DC	--	Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	I_F = max DC	Initial Level x 0.7	--
Reverse Current (I_R)	V_R = 5V	--	50 μA

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

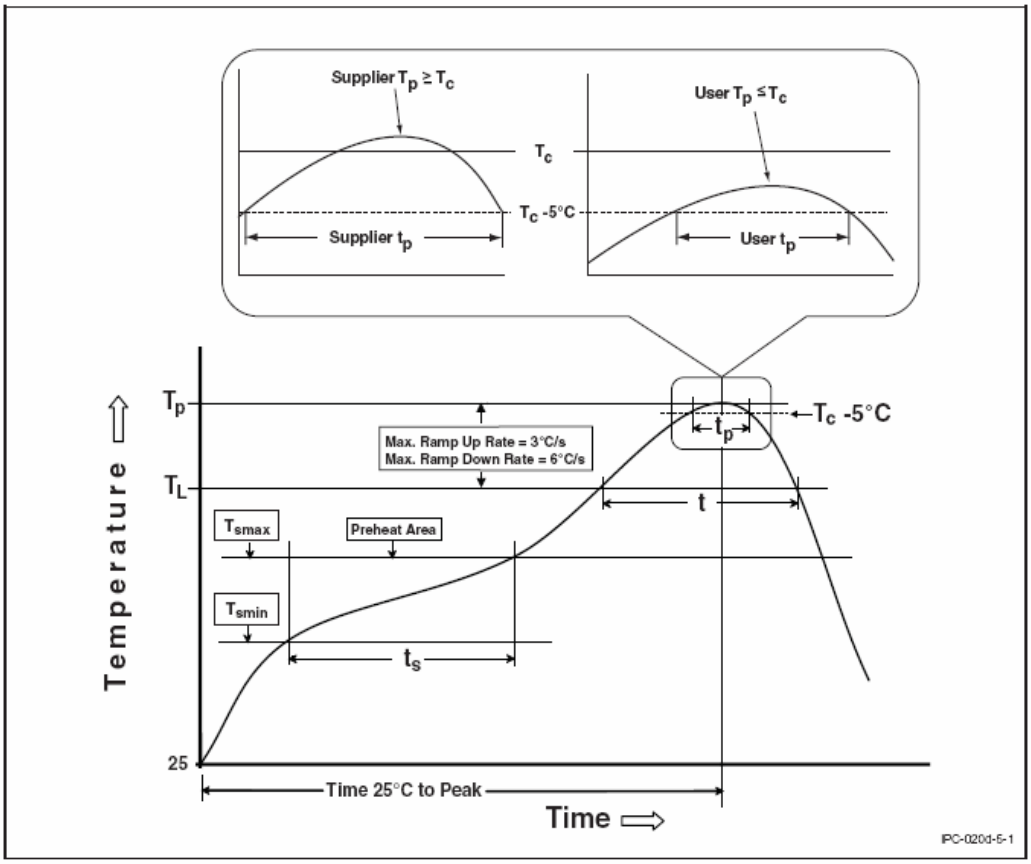
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

Reflow Soldering Condition

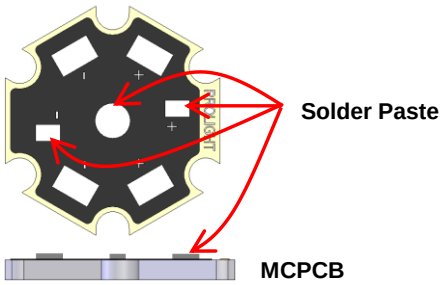
Profile Feature	Sn-Pb Eutectic Assembly	Low-Temp. & Pb-Free Assembly (58Bi-42Sn Eutectic Alloy)
Preheat & Soak		
Temperature min (T_{smin})	100 °C	90 °C
Temperature max (T_{smax})	150 °C	120 °C
Time (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Average Ramp-Up Rate (T_{smax} to T_P)	3 °C / second max.	2 °C / second max.
Liquidous temperature (T_L)	183°C	138°C
Time at liquidous (t_L)	60-150 seconds	20-50 seconds
Peak package body temperature (T_P)	235°C	185°C
Time (t_P) within 5°C of the specified classification temperature (T_C)	20 seconds	20 seconds
Average ramp-down rate (T_P to T_{smax})	6 °C/second max.	3 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	4 minutes max.



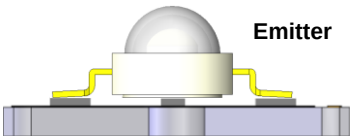
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Heat Plate Soldering Condition

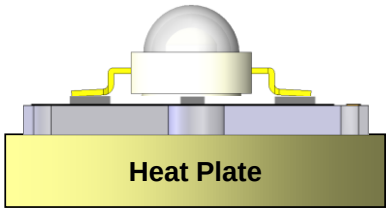
(1) Soldering Process for Solder Paste



Use Solder Mask to print Solder Paste on MCPCB.



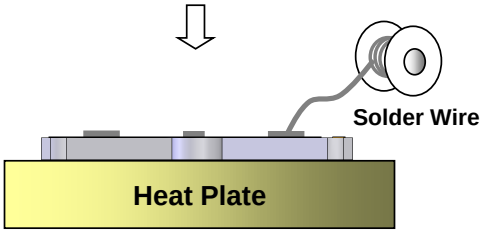
Place Emitter on MCPCB.



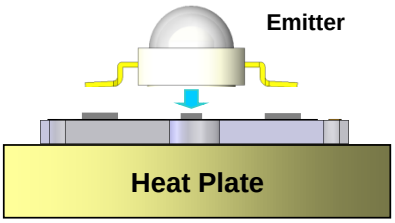
Put MCPCB on Heat Plate until Solder Paste melt.
The Solder Paste sould be melted within 10 seconds.
Take out MCPCB out from Heat Plate within 15 seconds.

(2) Soldering Process for Solder Wire

Put MCPCB on Heat Plate.



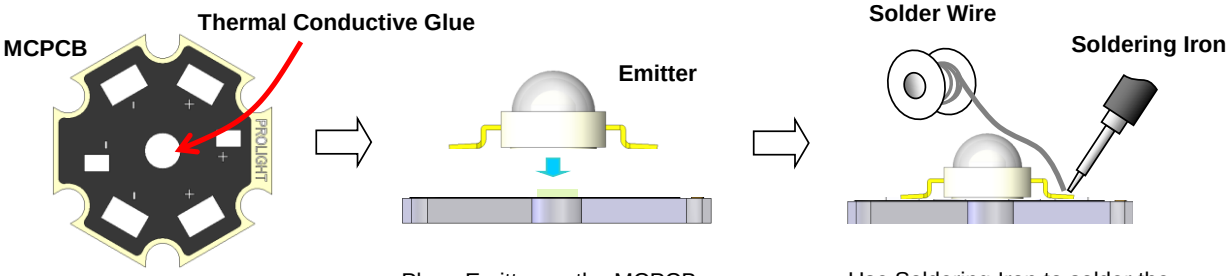
Place Solder Wire to the solder pad of MCPCB.



Put Emitter on MCPCB. Take the MCPCB out from Heat Plate within 10 seconds.

- Heat plate temperature: 230°C max for Lead Solder and 230°C max for Lead-Free Solder.
- We recommend using the 58Bi-42Sn eutectic alloy for low-temp. and lead free soldering (melting point = 138 °C).
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Manual Hand Soldering



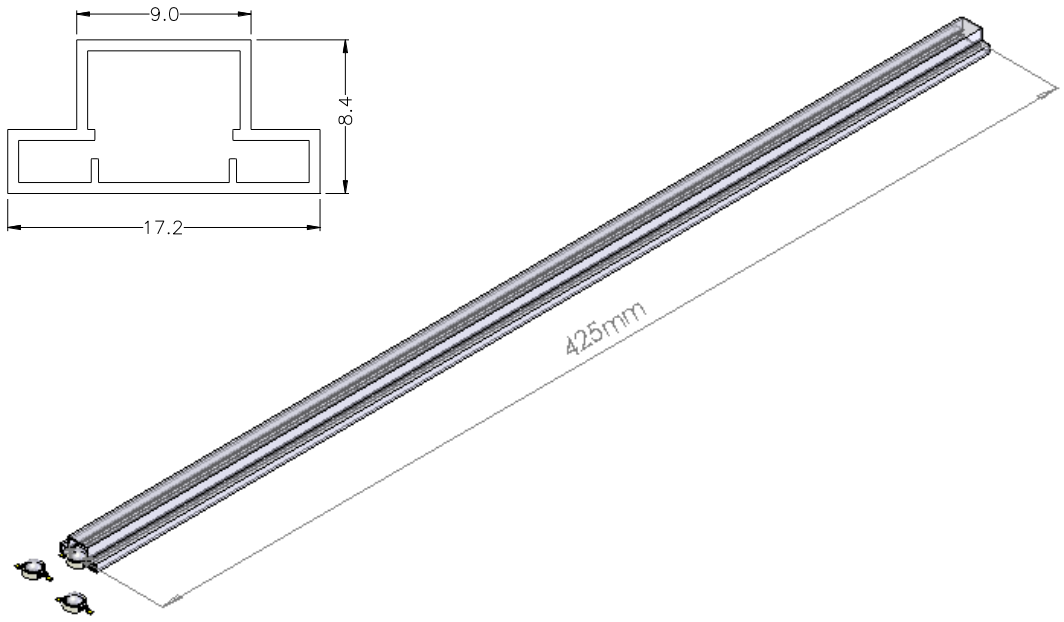
Place Thermal Comductive Glue on the MCPCB.

Place Emitter on the MCPCB.

Use Soldering Iron to solder the leads of Emtter within 5 seconds.

- For prototype builds or small series production runs it possible to place and solder the emitters by hand.
- Solder tip temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- Avoiding damage to the emitter or to the MCPCB dielectric layer. Damage to the epoxy layer can cause a short circuit in the array.
- Do not let the solder contact from solder pad to back-side of MCPCB. This one will cause a short circuit and damage emitter.

Emitter Tube Packaging



Notes:
1. 50 pieces per tube.
2. Drawing not to scale.
3. All dimensions are in millimeters.
4. All dimendions without tolerances are for reference only.

**Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

- Storage
  Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The slug is to be soldered. If not, please use the heat conductive adhesive.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets.
  http://www.prolightopto.com/